#### 502267102 03/13/2013

#### PATENT ASSIGNMENT

#### Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Hung-Hsuan Cheng	03/12/2013
Wei-Ling Chen	03/12/2013

#### **RECEIVING PARTY DATA**

Name:	uPI Semiconductor Corp.	
Street Address:	9F1, No.5, Taiyuan 1st St., Zhubei City	
City:	Hsinchu County	
State/Country:	TAIWAN	
Postal Code:	302	

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13798147

#### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER:	45459-US-PA	
NAME OF SUBMITTER:	Belinda Lee	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

Total Attachments: 3

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**PATENT** 

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# DECLARATION AND ASSIGNMENT FOR UTILITY OR DESIGN PATENT APPLICATION

Declaration Submitted With Initial Filing				
OR				
Declaration Submitted After Initial Filing (surcharge 3	7 CFR 1.16(f) required)			
(Title of the Invention)				
INTEGRATED CIRCUIT WITH MULTI-FUNCTIONAL PARAMETER SETTING AND MULTI-FUNCTIONAL PARAMETER SETTING METHOD THEREOF				
As a below named inventor (hereinafter designated as declare that:	the undersigned), I hereby			
This declaration is directed to:				
☑ The attached application,				
United States Application Number or PCT International	application number			
Filed on				
The above-identified application was made or authorized to	be made by me.			
believe I am the original inventor or an original joint inven he application.	tor of a claimed invention in			

### DECLARATION AND ASSIGNMENT

#### FOR UTILITY OR DESIGN PATENT APPLICATION

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS 1. uPI Semiconductor Corp.

of 9F.-1, No.5, Taiyuan 1st St., Zhubei City, Hsinchu County 302, Taiwan (R.O.C.)

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

PATENT REEL: 029990 FRAME: 0394

## DECLARATION AND ASSIGNMENT FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: Hung-Henar Cheng,	Date:	2013-03-12			
Legal Name of Sole or First Inventor: Hung-Hsuan Cheng					
Residence: Hsinchu County, Taiwan					
Mailing Address: c/o 9F1, No.5, Taiyuan 1st St., Zhubei City, Hsinchu County 302, Taiwan (R.O.C.)					
Signature: WEI - LING CHEN	Date:	2013-03-12			
Legal Name of Additional Joint Inventor, if any: Wei-Ling Chen					
Residence: Hsinchu County, Taiwan					
Mailing Address: c/o 9F1, No.5, Taiyuan 1st St., Zhubei City, Hsinchu County 302, Taiwan (R.O.C.)					